

Description

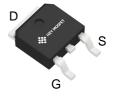
The AP3N5R0AH uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.



TO-252-2L

General Features

 $V_{DS} = 30V I_{D} = 100 A$

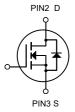
 $R_{DS(ON)} < 5m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



N-Channel MOSFET

Package Marking and Ordering Information

- working and ordering mornidation			
Product ID	Pack	Brand	Qty(PCS)
AP3N5R0AH	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating		Units
VDS	Drain- Source Voltage	30		V
VGS	Gate-Source Voltage	±20		V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	100		Α
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	57		Α
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	27	17	Α
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	23	14.5	Α
Ірм	Pulsed Drain Current ²	160		Α
EAS	Single Pulse Avalanche Energy ³	115.2		mJ
las	Avalanche Current	48		Α
P _D @T _C =25°C	Total Power Dissipation ⁴	53		W
P _D @T _A =25°C	Total Power Dissipation ⁴	6	2.4	W
Тѕтс	Storage Temperature Range	-55 to 175		°C
Tu	Operating Junction Temperature Range	-55 to 175		°C
R _θ JA	Thermal Resistance Junction-ambient (Steady State) ¹	62		°C/W
Reja	Thermal Resistance Junction-Ambient ¹ (t ≤10s)	25		°C/W
R _θ JC	Thermal Resistance Junction-Case ¹	2.8		°C/W



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVbss	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
∆BV _{DSS} /∆T _J	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.028		V/°C
.Rds(on)		V _{GS} =10V , I _D =30A		3.8	5.5	
. NDS(ON)	Static Drain-Source On- Resistance ²	V _{GS} =4.5V , I _D =15A		7.5	9	mΩ
V _G S(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
$\Delta V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-6.16		mV/°C
la	Dunin Course Leekens Course	V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	
Ipss	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA
Igss	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		22		S
R_g	Gate Resistance	Gate Resistance V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7	3.4	Ω
Q_g	Total Gate Charge (4.5V)			20		nC
Q _{gs}	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =15A		7.6		
Q_{gd}	Gate-Drain Charge	10-10A		7.2		
Td(on)	Turn-On Delay Time			7.8		ns
Tr	Rise Time	V _{DD} =15V , V _{GS} =10V ,		15		
Td(off)	Turn-Off Delay Time	-R _G =3.3 -I _D =15A		37.3		
T _f	Fall Time	ID-15A		10.6		
C _{iss}	Input Capacitance			2295		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V ,		267		pF
Crss	Reverse Transfer Capacitance	_f=1MHz		210		
Is	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force			80	Α
Ism	Pulsed Source Current ^{2,5}	Current			160	Α
Vsp	Diode Forward Voltage ²	Diode Forward Voltage ² V _{GS} =0V , I _S =1A , T _J =25°C			1	V
t _{rr}	Reverse Recovery Time	IF=30A, dI/dt=100A/µs,		14		nS
Qrr	Reverse Recovery Charge	T _J =25°C		5		nC

Note:

^{1.}The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width .The EAS data shows Max. rating .

^{3.} The test cond $\!\leq$ 300us , duty cycle ition is V_DD=25 $\!\leq$ V,V 2%GS =10V,L=0.1mH,I_AS=53.8A

^{4.}The power dissipation is limited by 175°C junction temperature

^{5.}The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics

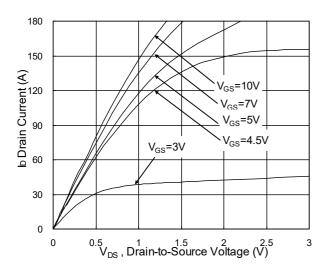


Fig.1 Typical Output Characteristics

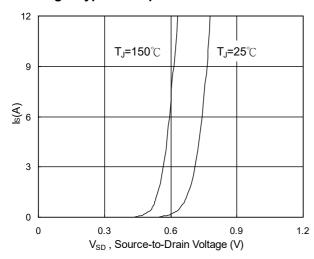


Fig.3 Forward Characteristics of Reverse

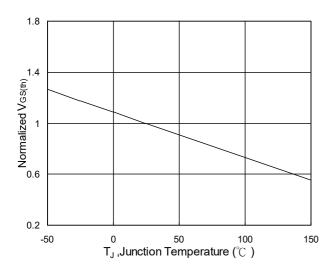


Fig.5 Normalized $V_{\text{GS(th)}}$ vs. T_{J}

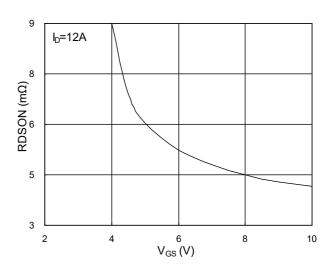


Fig.2 On-Resistance vs. G-S Voltage

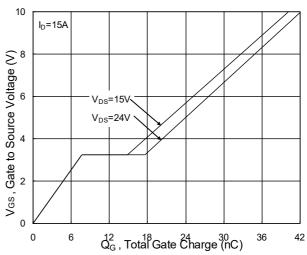


Fig.4 Gate-Charge Characteristics

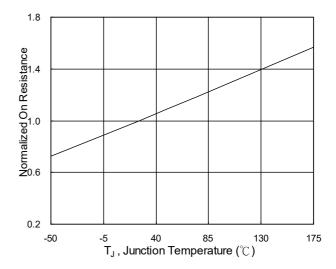
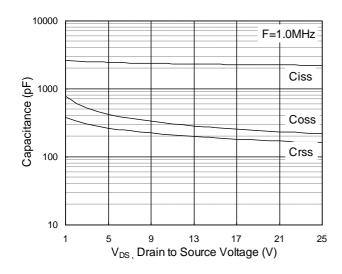


Fig.6 Normalized R_{DSON} vs. T_J





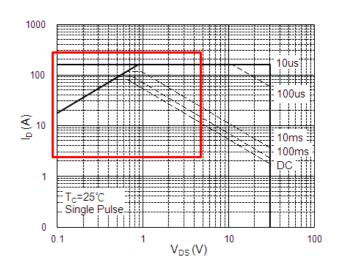


Fig.7 Capacitance

Fig.8 Safe Operating Area

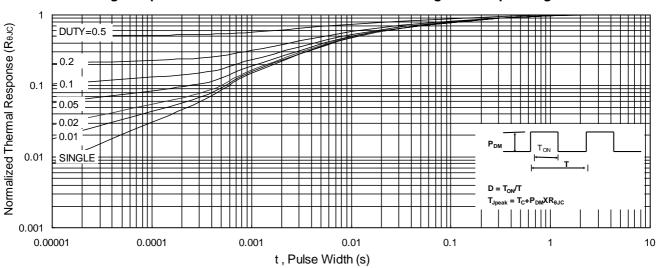


Fig.9 Normalized Maximum Transient Thermal Impedance

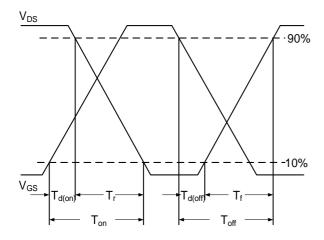


Fig.10 Switching Time Waveform

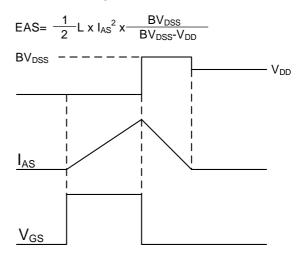
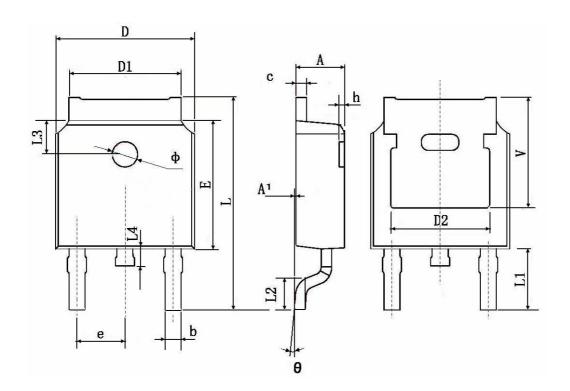


Fig.11 Unclamped Inductive Switching Waveform



TO252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	2.900 TYP.		TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	5.350 TYP. 0.211 TYP.		TYP.	



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